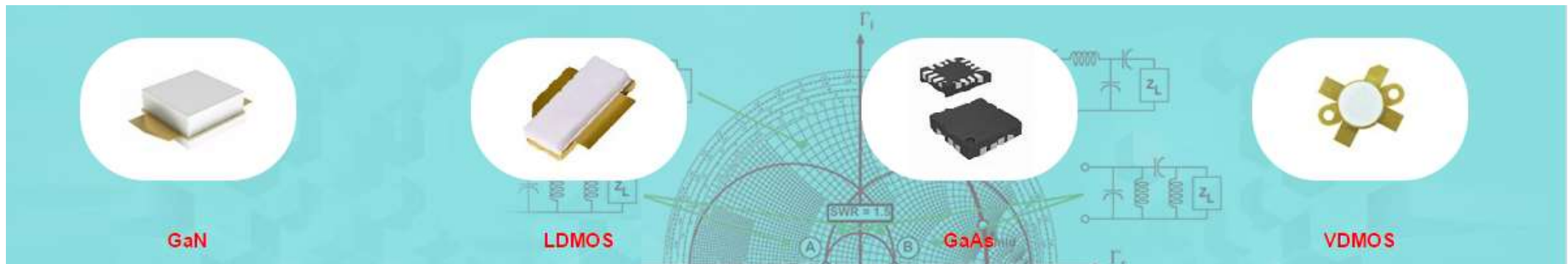


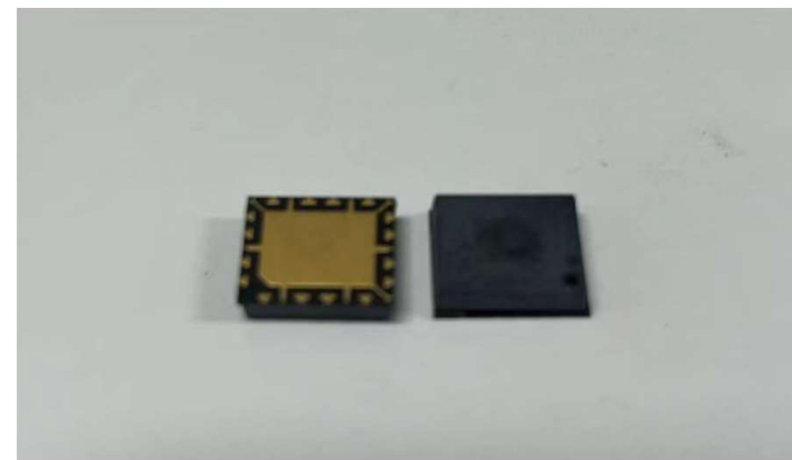
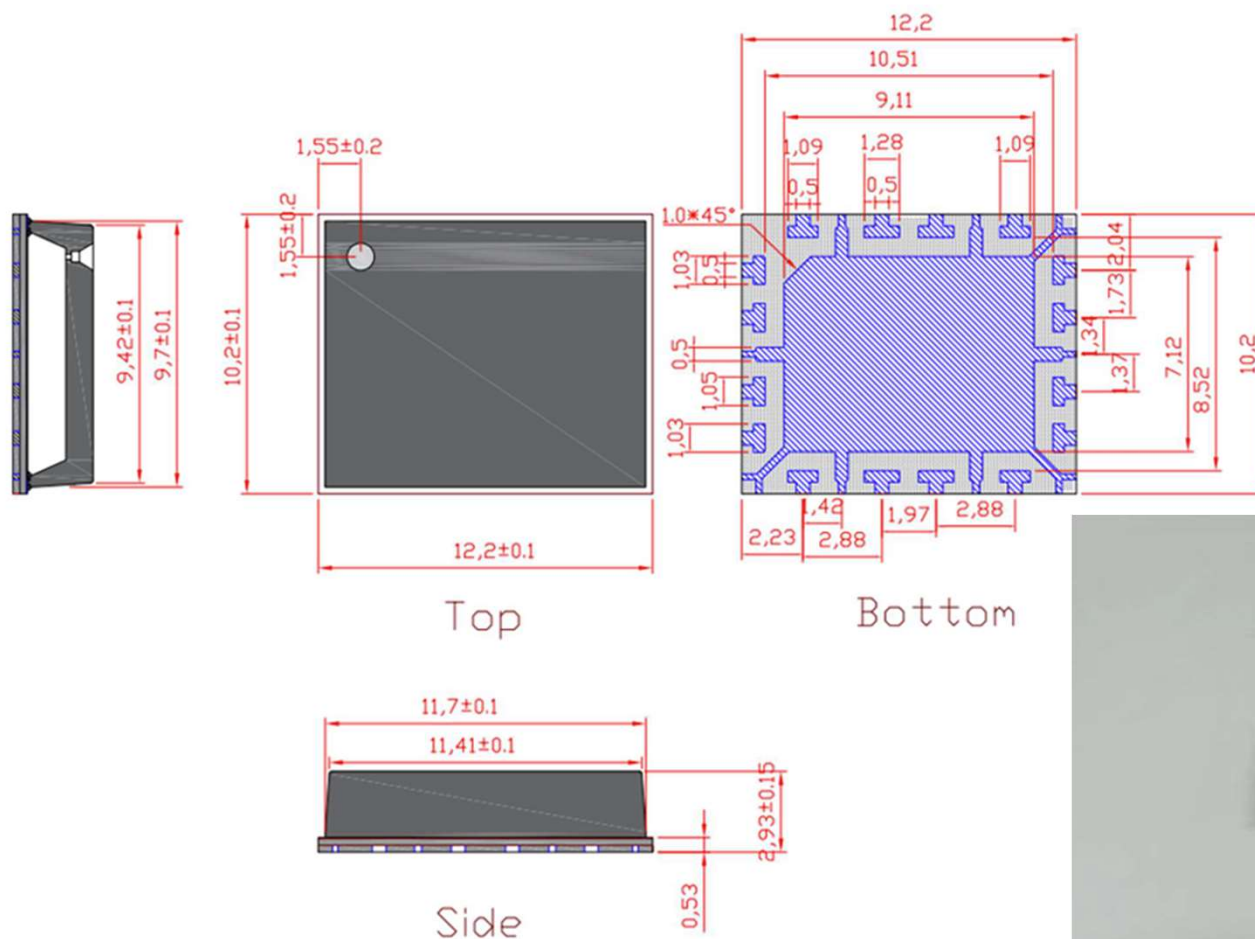
Guidance of C9 QFN soldered on heatsink

May-2024



Package Dimensions

Package details

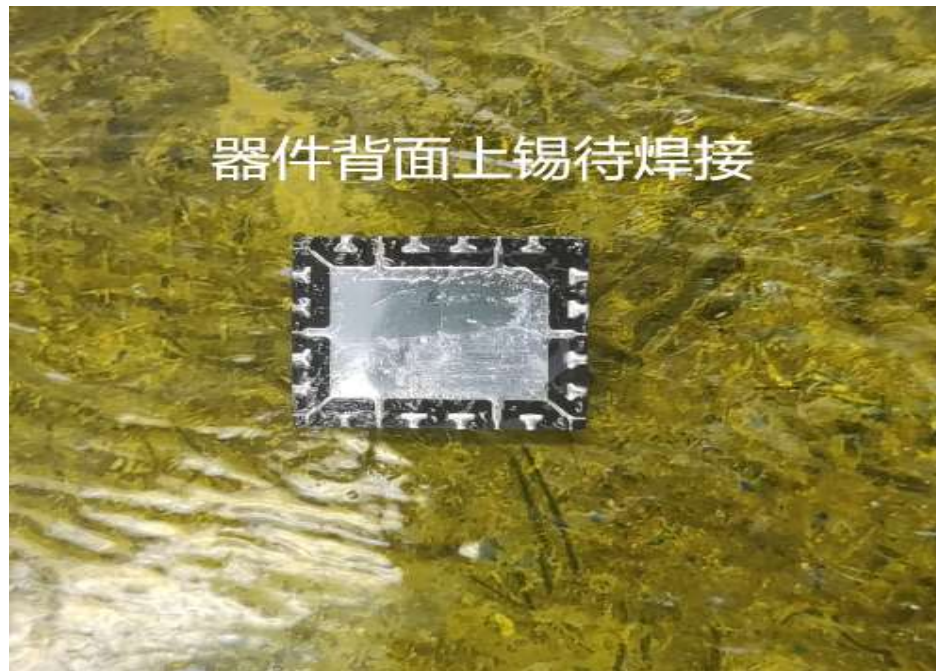


- C9 (12*10mm QFN)是Innogrations独立拥有设计专利的空腔表贴型低成本器件，具有低成本和高性能，高灵活性等特点。
- 为缩短散热路径，减小热阻，以可靠支持连续波工作，建议将C9直接焊接于金属散热器上，直接接地并高效散热。非连续波应用的场合，仍可通过常规的高密度过孔进行常规接地和散热

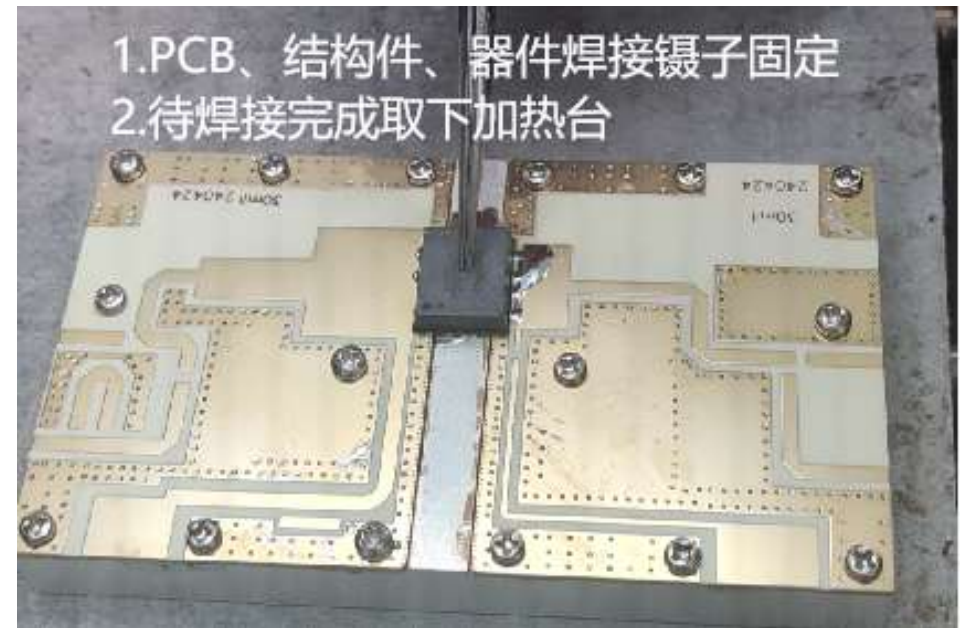


CONFIDENTIAL AND PROPRIETARY

STEP1



STEP2



Side view and top view after soldering

